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September 2015

FDMS86103L

N-Channel Shielded Gate PowerTrench[®] MOSFET 100 V, 81 A, 8 m Ω

Features

- Shielded Gate MOSFET Technology
- Max $r_{DS(on)} = 8 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 12 \text{ A}$
- Max $r_{DS(on)}$ = 11 m Ω at V_{GS} = 4.5 V, I_D = 10 A
- Advanced Package and Silicon combination for low r_{DS(on)} and high efficiency
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant

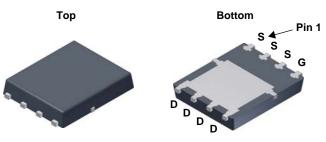


General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. This process has been optimized for the on-state resistance and yet maintain superior switching performance.

Application

■ DC-DC Conversion





S 2 D S 3 D G 4 D D

MOSFET Maximum Ratings $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter		Ratings	Units	
V _{DS}	Drain to Source Voltage			100	V
V_{GS}	Gate to Source Voltage			±20	V
	Drain Current -Continuous	T _C = 25 °C	(Note 5)	81	
	Drain Current -Continuous	T _C = 100 °C	(Note 5)	51	^
ID	-Continuous	T _A = 25 °C		12	Α
	-Pulsed		(Note 4)	414	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	312	mJ
В	Power Dissipation	T _C = 25 °C		104	W
P_{D}	Power Dissipation	T _A = 25 °C		2.5	VV
T _J , T _{STG}	Operating and Storage Junction Tempera	ture Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.2	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS86103L	FDMS86103L	Power 56	13 "	12 mm	3000 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted. **Parameter**

Off Cha	racteristics					
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		68		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate to Source Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V			±100	nA

Test Conditions

On Characteristics

Symbol

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1.0	1.9	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		-7		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 12 \text{ A}$		6.4	8	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$		8.4	11	mΩ
		$V_{GS} = 10 \text{ V}, I_D = 12 \text{ A}, T_J = 125 ^{\circ}\text{C}$		10.6	14	
9 _{FS}	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 12 \text{ A}$		59		S

Dynamic Characteristics

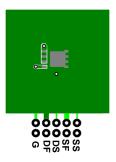
C _{iss}	Input Capacitance	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz	2790	3710	pF
C _{oss}	Output Capacitance		469	625	pF
C _{rss}	Reverse Transfer Capacitance		22	35	pF
R _g	Gate Resistance		1.3		Ω

Switching Characteristics

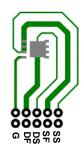
t _{d(on)}	Turn-On Delay Time		13	23	ns
t _r	Rise Time	V _{DD} = 50 V, I _D = 12 A,	7.2	15	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	35	57	ns
t _f	Fall Time		6	13	ns
Q_{g}	Total Gate Charge	V _{GS} = 0 V to 10 V	43	60	nC
Q_{g}	Total Gate Charge	$V_{GS} = 0 \text{ V to 5 V}$ $V_{DD} = 50 \text{ V},$	23	32	nC
Q_{gs}	Gate to Source Charge	I _D = 12 A	7.5		nC
Q_{gd}	Gate to Drain "Miller" Charge		7		nC

Drain-Source Diode Characteristics

V _{SD} Source to Drain Diod	Source to Drain Diade, Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2 \text{ A}$ (Note 2))	0.70	1.2	\/
	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 12 \text{ A}$ (Note 2)	0.78	1.3	V
t _{rr}	Reverse Recovery Time	I _F = 12 A. di/dt = 100 A/μs		57	90	ns
Q _{rr}	Reverse Recovery Charge	- 1 _F = 12 A, αι/αι = 100 A/μS		68	108	nC



a. 50 °C/W when mounted on a 1 in² pad of 2 oz copper.



b. 125 °C/W when mounted on a minimum pad of 2 oz copper.

Min. Typ. Max. Units

- 2. Pulse Test: Pulse Width < 300 $\mu s,$ Duty cycle < 2.0%.
- 3. Starting $T_J = 25$ °C, L = 1 mH, $I_{AS} = 25$ A, $V_{DD} = 90$ V, $V_{GS} = 10$ V
- 4. Pulsed Id please refer to Fig 11 SOA graph for more details.
- 5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

Typical Characteristics T_J = 25 °C unless otherwise noted.

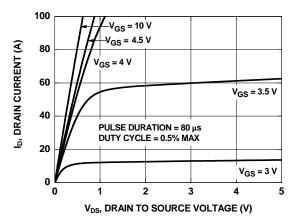


Figure 1. On-Region Characteristics

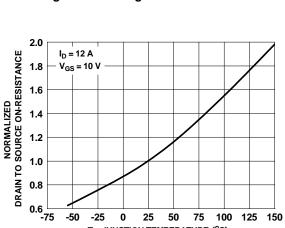


Figure 3. Normalized On-Resistance vs Junction Temperature

25 50

T_J, JUNCTION TEMPERATURE (°C)

-50

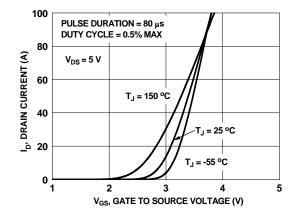


Figure 5. Transfer Characteristics

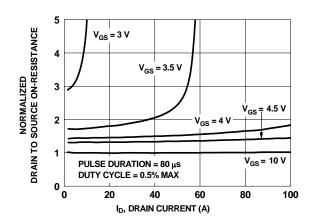


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

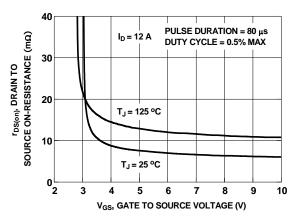


Figure 4. On-Resistance vs Gate to Source Voltage

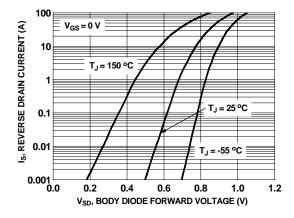


Figure 6. Source to Drain Diode **Forward Voltage vs Source Current**

Typical Characteristics $T_J = 25 \, ^{\circ}\text{C}$ unless otherwise noted.

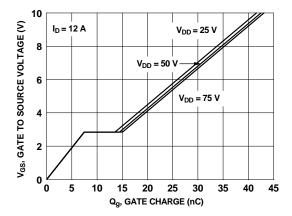


Figure 7. Gate Charge Characteristics

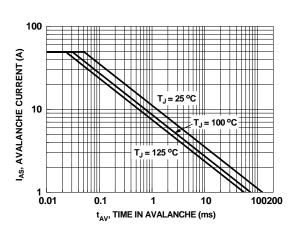


Figure 9. Unclamped Inductive Switching Capability

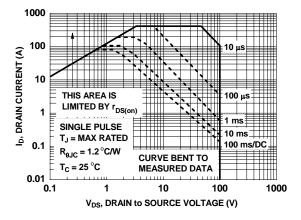


Figure 11. Forward Bias Safe Operating Area

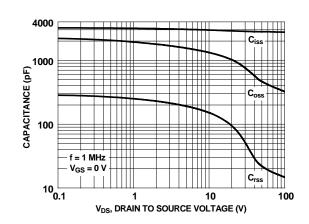


Figure 8. Capacitance vs Drain to Source Voltage

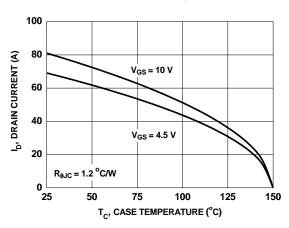


Figure 10. Maximum Continuous Drain Current vs Case Temperature

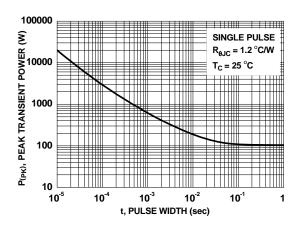


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25$ °C unless otherwise noted.

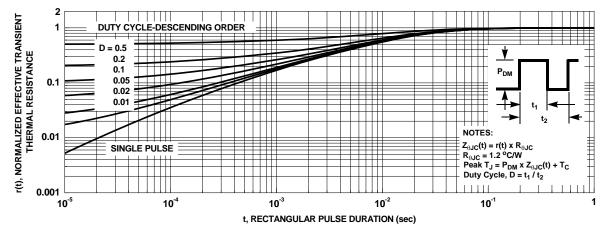
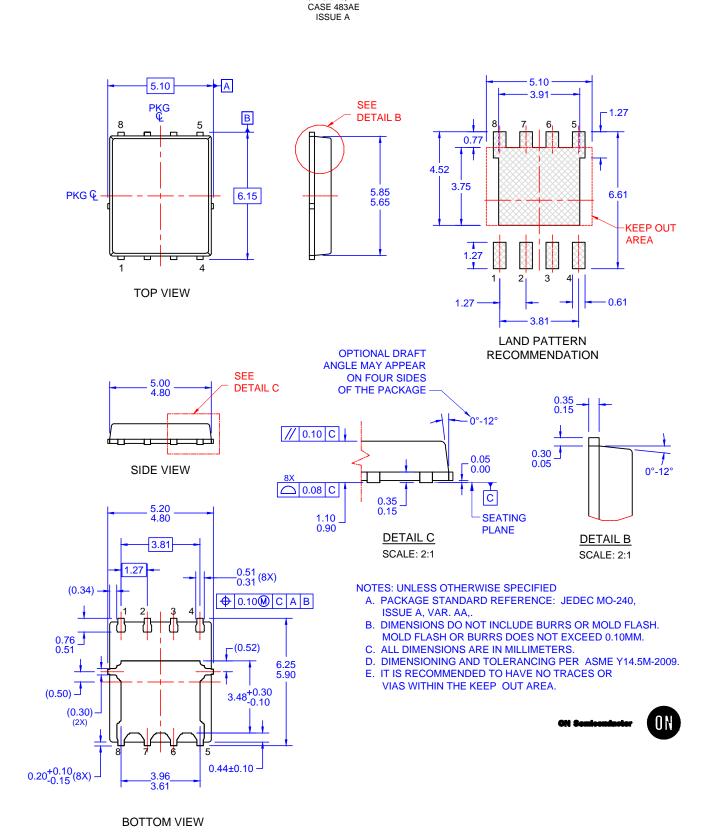


Figure 13. Junction-to-Ambient Transient Thermal Response Curve



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